

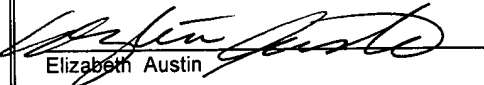
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Sean Michael Malolepszy, et al.**
Serial No.: **TBD**
Filed: **Herewith**
For: **Bond Surface Conditioning System For
Improved Bondability**

Docket No.: **TI-33434.1**
Examiner: **TBD**
Art Unit.: **TBD**
Conf. No.: **TBD**

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner For Patents
Attn: Official Drafts Person
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.	
 Elizabeth Austin	<u>7/1/2003</u> Date

Dear Sir:

Submitted herewith are 5 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Texas Instruments Incorporated
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Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682